TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

TPC8210

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Low drain-source ON resistance: $RDS(ON) = 11 \text{ m}\Omega(typ.)$

• High forward transfer admittance: $|Y_{fs}| = 13 \text{ S (typ.)}$

• Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$

• Enhancement-mode: $V_{th} = 1.3 \text{ to } 2.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

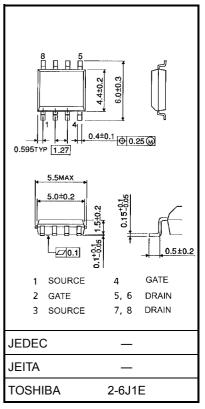
Maximum Ratings (Ta = 25°C)

Char	racteristics	Symbol	Rating	Unit		
Drain-source vol	tage	V_{DSS}	30	V		
Drain-gate voltag	ge (R _{GS} = 20 kΩ)	V _{DGR}	30	V		
Gate-source volt	age	V _{GSS}	±20	V		
Drain current	D C (Note 1)	I _D	8	Α		
	Pulse (Note 1)	I _{DP}	32	A		
Drain power dissipation	Single-device operation (Note 3a)	P _{D (1)}	1.5	W		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P _{D(2)}	1.1	VV		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P _{D (1)}	0.75	W		
	Single-device value at dual operation (Note 3b)	P _{D (2)}	0.45			
Single pulse ava	lanche energy (Note 4)	E _{AS}	83.2	mJ		
Avalanche curre	nt	I _{AR}	8	Α		
Repetitive avalar Single-device va	nche energy lue at dual operation (Note 2a, 3b, 5)	E _{AR}	0.1	mJ		
Channel tempera	ature	T _{ch}	150	°C		
Storage tempera	ture range	T _{stg}	-55 to 150	°C		

Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

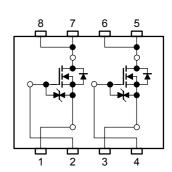
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.08 g (typ.)

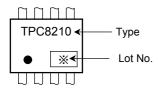
Circuit Configuration



Thermal Characteristics

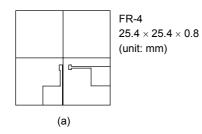
Characteristics	Symbol	Max	Unit		
The small resistance about 140 cushicut	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	83.3		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R _{th} (ch-a) (2)	114 °C/W		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R _{th (ch-a) (1)}	167	C/VV	
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R _{th (ch-a) (2)}	278		

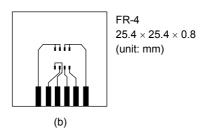
Marking (Note 6)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

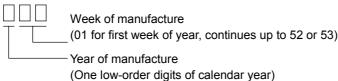




- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)

Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 8 A
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on lower left of the marking indicates Pin 1.
 - Weekly code: (Three digits)



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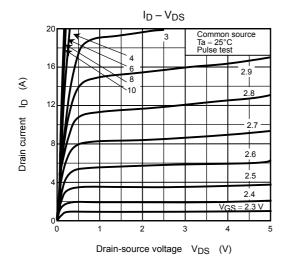
Electrical Characteristics (Ta = 25°C)

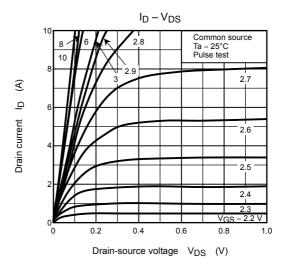
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-OFF	Drain cut-OFF current		V _{DS} = 30 V, V _{GS} = 0 V		_	10	μA
Drain-source breakdown voltage		V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	30	_	I	V
		V _{(BR) DSS}	I_D = 10 mA, V_{GS} = -20 V	15	_		
Gate threshold v	oltage/	V_{th}	V _{DS} = 10 V, I _D = 1 mA	1.3	_	2.5	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 4.5 V, I _D = 4 A		13	20	mO.
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A		11	15	mΩ
Forward transfer	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 4 A	6.5	13	_	S
Input capacitano	e	C _{iss}		_	3530	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	495	_	pF
Output capacitance		Coss		_	580	_	
Switching time	Rise time	tr	V_{GS} $\begin{array}{c} 10 \text{ V} \\ 0 \text{ V} \\ \end{array}$ $\begin{array}{c} I_{D} = 4 \text{ A} \\ 0 \text{ VOUT} \\ \end{array}$ $\begin{array}{c} V_{C} \\ V_{C} \\ \end{array}$ $\begin{array}{c} V_{C} \\ V_$		26	-	
	Turn-ON time	t _{on}		1	39	ı	ns
	Fall time	t _f			32	-	
	Turn-OFF time	t _{off}			115	-	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 24 V, V _{GS} = 10 V, I _D = 8 A	_	75	_	
Gate-source charge		Q_{gs}		_	6	_	nC
Gate-drain ("miller") charge		Q_{gd}		_	19	_	

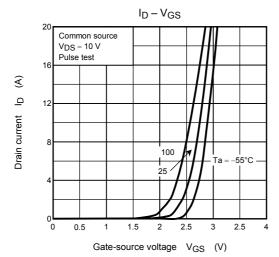
Source-Drain Ratings and Characteristics (Ta = 25°C)

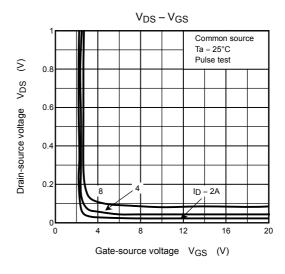
Characte	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	_	_	_	32	Α
Forward voltage (diode) V _{DSF}		V_{DSF}	I _{DR} = 8 A, V _{GS} = 0 V	_	_	-1.2	V

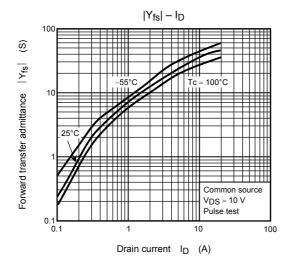
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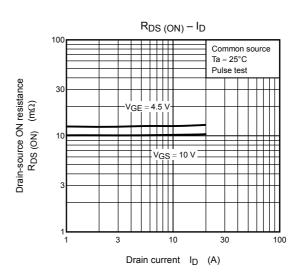


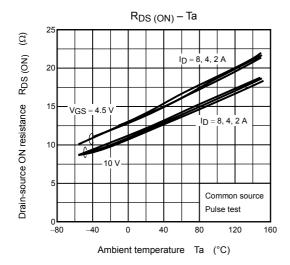


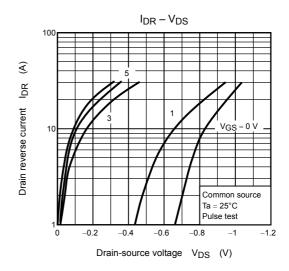


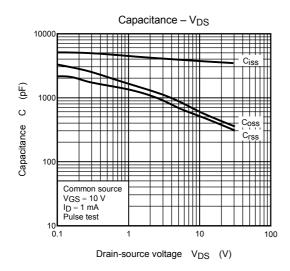


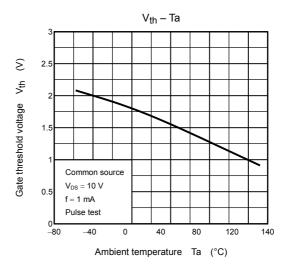


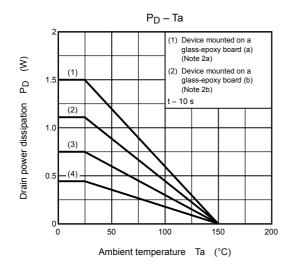


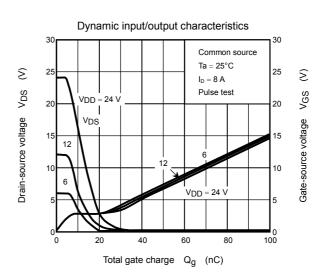


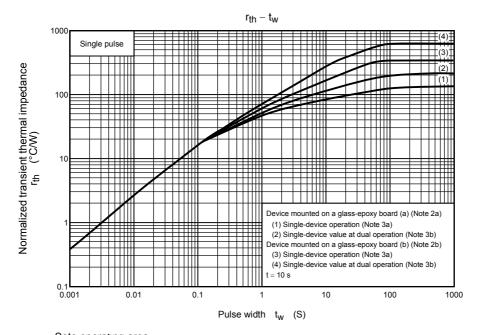


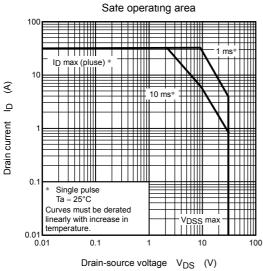












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